

Low Skew, Dual, 1-to-5

## 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

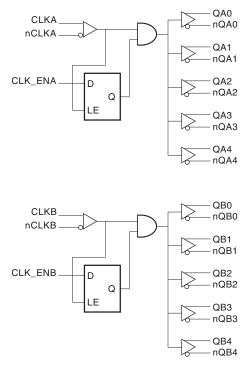
### **GENERAL DESCRIPTION**

The ICS85310I-31 is a low skew, high performance dual 1-to-5 Differential-to-2.5V/3.3V ECL/LVPECL Fanout Buffer . The CLKx, nCLKx pairs can accept most standard differential input levels. The ICS85310I-31 is characterized to operate from either a 2.5V or a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS85310I-31 ideal for those clock distribution applications demanding well defined performance and repeatability.

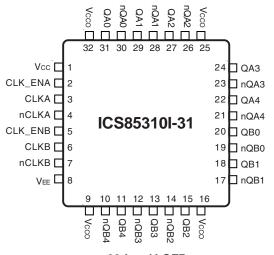
### **F**EATURES

- Two differential 2.5V/3.3V LVPECL / ECL bank outputs
- · Two differential clock input pairs
- CLKx, nCLKx pairs can accept the following differential input levels: LVPECL, LVDS, LVHSTL, SSTL, HCSL
- Maximum output frequency: 700MHz
- Translates any single ended input signal to 3.3V LVPECL levels with resistor bias on nCLKx input
- Output skew: 25ps (typical)
- Part-to-part skew: 270ps (typical)
- Propagation delay: 1.7ns (typical)
- Additive phase jitter, RMS: <0.13ps (typical)
- LVPECL mode operating voltage supply range:  $V_{CC} = 2.375V$  to 3.8V,  $V_{FF} = 0V$
- ECL mode operating voltage supply range:
   V<sub>CC</sub> = 0V, V<sub>FF</sub> = -3.8V to -2.375V
- -40°C to 85°C ambient operating temperature
- · Lead-Free package fully RoHS compliant

### **BLOCK DIAGRAM**



### PIN ASSIGNMENT



32-Lead LQFP
7mm x 7mm x 1.4mm package body
Y Package
Top View



Low Skew, Dual, 1-to-5 2.5V/3.3V Differential-to-ECL/LVPECL Fanout Buffer

### TABLE 1. PIN DESCRIPTIONS

Number	Name	Ту	ре	Description
1	V <sub>cc</sub>	Power		Core supply pin.
2	CLK_ENA	Unused	Pullup	Synchronizing clock enable. LVCMOS/LVTTL interface levels.
3	CLKA	Input	Pulldown	Non-inverting differential clock input.
4	nCLKA	Input	Pullup	Inverting differential clock input.
5	CLK_ENB	Unused	Pullup	Synchronizing clock enable. LVCMOS/LVTTL interface levels.
6	CLKB	Input	Pulldown	Non-inverting differential clock input.
7	nCLKB	Input	Pullup	Inverting differential clock input.
8	$V_{EE}$	Power		Negative supply pin.
9, 16, 25, 32	V <sub>cco</sub>	Power		Output supply pins.
10, 11	nQB4, QB4	Output		Differential output pair. LVPECL interface levels.
12, 13	nQB3, QB3	Output		Differential output pair. LVPECL interface levels.
14, 15	nQB2, QB2	Output		Differential output pair. LVPECL interface levels.
17, 18	nQB1, QB1	Output		Differential output pair. LVPECL interface levels.
19, 20	nQB0, QB0	Output		Differential output pair. LVPECL interface levels.
21, 22	nQA4, QA4	Output		Differential output pair. LVPECL interface levels.
23, 24	nQA3, QA3	Output		Differential output pair. LVPECL interface levels.
26, 27	nQA2, QA2	Output		Differential output pair. LVPECL interface levels.
28, 29	nQA1, QA1	Output		Differential output pair. LVPECL interface levels.
30, 31	nQA0, QA0	Output		Differential output pair. LVPECL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

### Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
R <sub>PULLUP</sub>	Input Pullup Resistor			51		kΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		kΩ



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TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs	Outputs				
CLK_ENA, CLK_ENB	QA0:QA4, QB0:QB4	nQA0:nQA4, nQB0:nQB4			
0	Disabled; LOW	Disabled; HIGH			
1	Enabled	Enabled			

After CLK EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as shown in Figure 1.

In the active mode, the state of the outputs are a function of the CLKA, nCLKA and CLKB, nCLKB inputs as described in Table 3B.

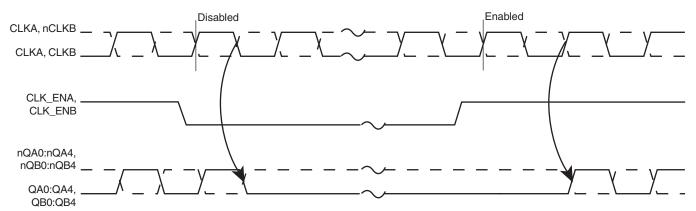


FIGURE 1. CLK\_EN TIMING DIAGRAM

TABLE 3B. CLOCK INPUT FUNCTION TABLE

In	puts	Ou	ıtputs		
CLKA or CLKB	nCLKA or nCLKB	QA0:QA4, QB0:QB4	nQA0:nQA4, nQB0:nQB4	Input to Output Mode	Polarity
0	1	LOW	HIGH	Differential to Differential	Non Inverting
1	0	HIGH	LOW	Differential to Differential	Non Inverting
0	Biased; NOTE 1	LOW	HIGH	Single Ended to Differential	Non Inverting
1	Biased; NOTE 1	HIGH	LOW	Single Ended to Differential	Non Inverting
Biased; NOTE 1	0	HIGH	LOW	Single Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information "Wiring The Differential Input To Accept Single Ended Levels".



Low Skew, Dual, 1-TO-5

## 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

#### ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V<sub>CC</sub> 4.6V

Inputs,  $V_{i}$  -0.5V to  $V_{CC}$  + 0.5V

Outputs, I<sub>O</sub>

Continuous Current 50mA Surge Current 100mA

Package Thermal Impedance, θ<sub>IA</sub> 47.9°C/W (0 Ifpm)

Storage Temperature, T<sub>STG</sub> -65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Table 4A. Power Supply DC Characteristics,  $V_{CC}$ ,  $V_{CCO} = 2.375V$  to 3.8V, Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>cc</sub>	Core Supply Voltage		2.375	3.3	3.8	V
V <sub>cco</sub>	Output Supply Voltage		2.375	3.3	3.8	V
I <sub>EE</sub>	Power Supply Current				120	mA

### Table 4B. LVCMOS / LVTTL DC Characteristics, $V_{CC}$ , $V_{CCO}$ = 2.375V to 3.8V, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	CLK_ENA, CLK_ENB		2		V <sub>cc</sub> + 0.3	V
V <sub>IL</sub>	Input Low Voltage	CLK_ENA, CLK_ENB		-0.3		0.8	V
I <sub>IH</sub>	Input High Current	CLK_ENA, CLK_ENB	$V_{CC} = V_{IN} = 3.8V$			5	μΑ
I	Input Low Current	CLK_ENA, CLK_ENB	$V_{CC} = 3.8V, V_{IN} = 0V$	-150			μΑ

Table 4C. Differential DC Characteristics,  $V_{CC}$ ,  $V_{CCO} = 2.375V$  to 3.8V, Ta = -40°C to 85°C

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
	Input High Current	CLKA, CLKB	$V_{CC} = V_{IN} = 3.8V$			150	μΑ
Input High Current		nCLKA, nCLKB	$V_{CC} = V_{IN} = 3.8V$			5	μΑ
	Input Low Current	CLKA, CLKB	$V_{CC} = 3.8V, V_{IN} = 0V$	-5			μΑ
I <sub>IL</sub>	I <sub>IL</sub> Input Low Current	nCLKA, nCLKB	$V_{CC} = 3.8V, V_{IN} = 0V$	-150			μΑ
V <sub>PP</sub>	Peak-to-Peak Input Voltage			0.15		1.3	V
V <sub>CMR</sub>	Common Mode Input Voltage; NOTE 1, 2			V <sub>EE</sub> + 0.5		V <sub>cc</sub> - 0.85	V

NOTE 1: Common mode voltage is defined as V<sub>IH</sub>.

NOTE 2: For single ended applications, the maximum input voltage for CLKA, nCLKA and CLKB, nCLKB is  $V_{cc}$  + 0.3V.



## Low Skew, Dual, 1-to-5 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

Table 4D. LVPECL DC Characteristics,  $V_{CC}$ ,  $V_{CCO} = 2.375 V$  to 3.8V, Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V <sub>OH</sub>	Output High Voltage; NOTE 1		V <sub>cco</sub> - 1.4		V <sub>cco</sub> - 0.9	V
V <sub>OL</sub>	Output Low Voltage; NOTE 1		V <sub>cco</sub> - 2.0		V <sub>cco</sub> - 1.7	V
V <sub>SWING</sub>	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{cco}$  - 2V.

Table 5. AC Characteristics,  $V_{CC}$ ,  $V_{CCO} = 2.375V$  to 3.8V, Ta = -40°C to 85°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency				700	MHz
$t_{\scriptscriptstyle{ extsf{PD}}}$	Propagation Delay; NOTE 1	<i>f</i> ≤ 500MHz		1.7	2.2	ns
tsk(o)	Output Skew; NOTE 2, 4			25	50	ps
tsk(pp)	Part-to-Part Skew; NOTE 3, 4			270	550	ps
<i>t</i> jit	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section			<0.13		ps
t <sub>R</sub>	Output Rise Time	20% to 80%	200		700	ps
t <sub>F</sub>	Output Fall Time	20% to 80%	200		700	ps
odc	Output Duty Cycle		47		53	%

All parameters measured at 500MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



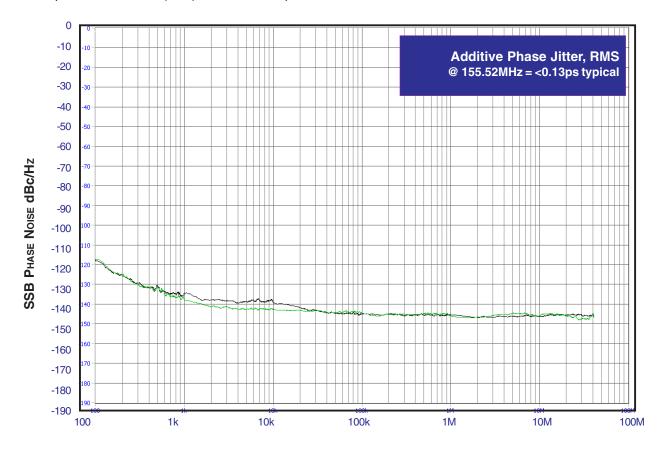
Low Skew, Dual, 1-TO-5

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### **ADDITIVE PHASE JITTER**

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in

the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



OFFSET FROM CARRIER FREQUENCY (Hz)

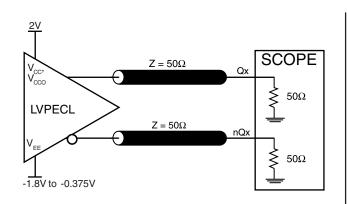
As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated

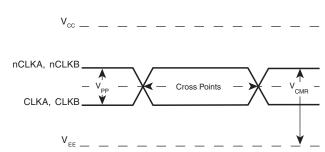
above. The device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.



## Low Skew, Dual, 1-to-5 2.5V/3.3V Differential-to-ECL/LVPECL Fanout Buffer

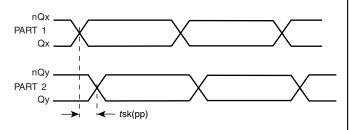
## PARAMETER MEASUREMENT INFORMATION

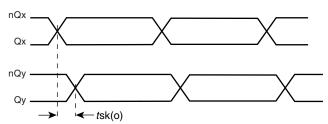




### 3.3V OUTPUT LOAD AC TEST CIRCUIT

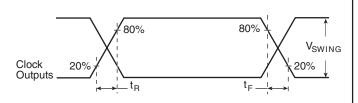
DIFFERENTIAL INPUT LEVEL

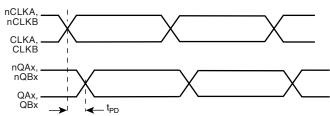




### PART-TO-PART SKEW

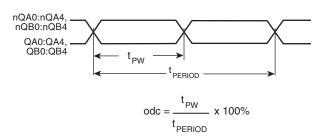
**OUTPUT SKEW** 





### **OUTPUT RISE/FALL TIME**

PROPAGATION DELAY



**OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD** 

Low Skew, Dual, 1-TO-5

## 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

### **APPLICATION INFORMATION**

### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 2 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{cc}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{\rm CC}$  = 3.3V, V\_REF should be 1.25V and R2/R1 = 0.609.

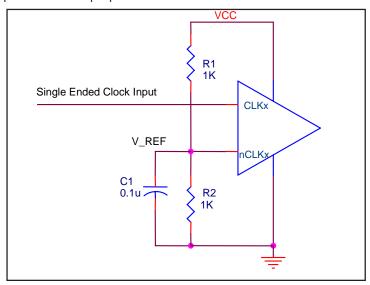


FIGURE 2. SINGLE ENDED SIGNAL DRIVING DIFFERENTIAL INPUT

### **TERMINATION FOR 3.3V LVPECL OUTPUTS**

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

 $50\Omega$  transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 3A and 3B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

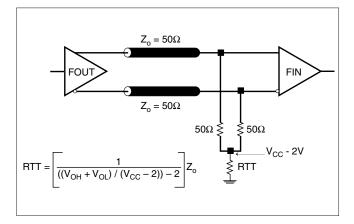


FIGURE 3A. LVPECL OUTPUT TERMINATION

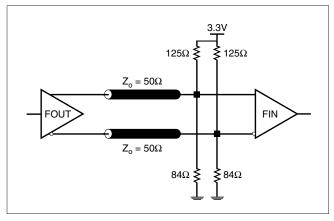


FIGURE 3B. LVPECL OUTPUT TERMINATION



## Low Skew, Dual, 1-to-5 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

### **TERMINATION FOR 2.5V LVPECL OUTPUTS**

Figure 4A and Figure 4B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating  $50\Omega$  to  $V_{cc}$  - 2V. For  $V_{cc}$  = 2.5V, the  $V_{cc}$  - 2V is very close to ground level. The R3 in Figure 4B can be eliminated and the termination is shown in Figure 4C.

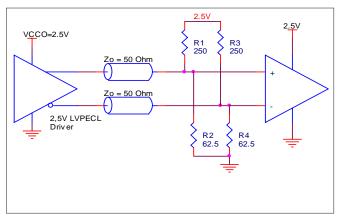


FIGURE 4A. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

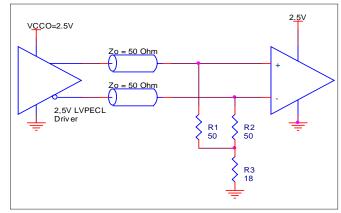


FIGURE 4B. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

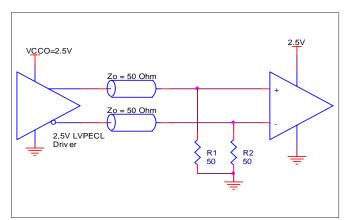


FIGURE 4C. 2.5V LVPECL TERMINATION EXAMPLE

Low Skew, Dual, 1-to-5

## 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

### DIFFERENTIAL CLOCK INPUT INTERFACE

The CLK /nCLK accepts LVDS, LVPECL, LVHSTL, SSTL, HCSL and other differential signals. Both  $V_{\text{SWING}}$  and  $V_{\text{OH}}$  must meet the  $V_{\text{PP}}$  and  $V_{\text{CMR}}$  input requirements. Figures 5A to 5E show interface examples for the CLK/nCLK input driven by the most common driver types. The input interfaces suggested here are

examples only. Please consult with the vendor of the driver component to confirm the driver termination requirements. For example in *Figure 5A*, the input termination applies for LVHSTL drivers. If you are using an LVHSTL driver from another vendor, use their termination recommendation.

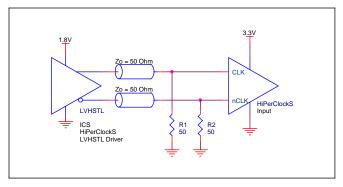


FIGURE 5A. CLK/nCLK INPUT DRIVEN BY LVHSTL DRIVER

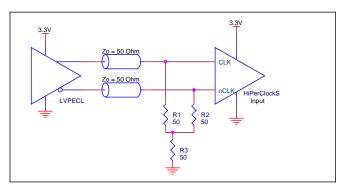


FIGURE 5B. CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

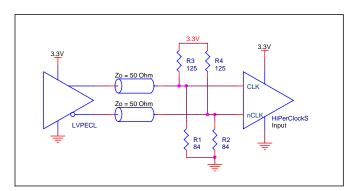


FIGURE 5C. CLK/nCLK INPUT DRIVEN BY 3.3V LVPECL DRIVER

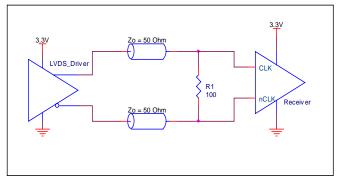


FIGURE 5D. CLK/nCLK INPUT DRIVEN BY 3.3V LVDS DRIVER

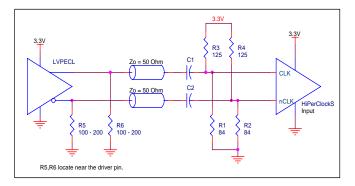


FIGURE 5E. CLK/nCLK INPUT DRIVEN BY
3.3V LVPECL DRIVER WITH AC COUPLE



Low Skew, Dual, 1-TO-5

## 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

### Power Considerations

This section provides information on power dissipation and junction temperature for the ICS85310I-31. Equations and example calculations are also provided.

#### 1. Power Dissipation.

The total power dissipation for the ICS85310I-31 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.8V$ , which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> = V<sub>CC\_MAX</sub> \* I<sub>EE\_MAX</sub> = 3.8V \* 120mA = 456mW
- Power (outputs)<sub>MAX</sub> = 30mW/Loaded Output pair
   If all outputs are loaded, the total power is 10 \* 30mW = 300mW

Total Power MAX (3.8V, with all outputs switching) = 456mW + 300mW = 756mW

#### 2. Junction Temperature.

Junction temperature, Tj, is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for the devices is 125°C.

The equation for Tj is as follows: Tj =  $\theta_{IA}$  \* Pd\_total + T<sub>A</sub>

Tj = Junction Temperature

 $\theta_{IA}$  = Junction-to-Ambient Thermal Resistance

Pd\_total = Total Device Power Dissipation (example calculation is in section 1 above)

 $T_A =$  Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 42.1°C/W per Table 6 below.

Therefore, Tj for an ambient temperature of 85°C with all outputs switching is:

 $85^{\circ}\text{C} + 0.756\text{W} * 42.1^{\circ}\text{C/W} = 116.8^{\circ}\text{C}$ . This is below the limit of  $125^{\circ}\text{C}$ .

This calculation is only an example. Tj will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

Table 6. Thermal Resistance  $\theta_{\text{JA}}$  for 32-pin LQFP, Forced Convection

### $\theta_{_{JA}}$ by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

Low Skew, Dual, 1-to-5

## 2.5V/3.3V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

#### 3. Calculations and Equations.

LVPECL output driver circuit and termination are shown in Figure 6.

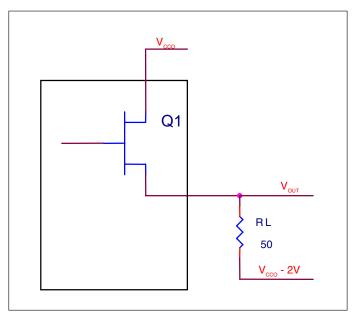


FIGURE 6. LVPECL Driver Circuit and Termination

To calculate worst case power dissipation into the load, use the following equations which assume a  $50\Omega$  load, and a termination voltage of  $V_{CCO}$  - 2V.

• For logic high, 
$$V_{OUT} = V_{OH\_MAX} = V_{CCO\_MAX} - 0.9V$$

$$(V_{CCO\_MAX} - V_{OH\_MAX}) = 0.9V$$

• For logic low, 
$$V_{OUT} = V_{OL\_MAX} = V_{CCO\_MAX} - 1.7V$$

$$(V_{CCO\_MAX} - V_{OL\_MAX}) = 1.7V$$

$$Pd\_H = [(V_{OH\_MAX} - (V_{CCO\_MAX} - 2V))/R_{L}] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OH\_MAX}))/R_{L}] * (V_{CCO\_MAX} - V_{OH\_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = 19.8mW$$

$$Pd_{L} = [(V_{OL\_MAX} - (V_{CCO\_MAX} - 2V))/R_{L}] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CCO\_MAX} - V_{OL\_MAX}))/R_{L}] * (V_{CCO\_MAX} - V_{OL\_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = Pd\_H + Pd\_L = 30mW



## Low Skew, Dual, 1-to-5 2.5V/3.3V Differential-to-ECL/LVPECL Fanout Buffer

## **RELIABILITY INFORMATION**

Table 7.  $\theta_{\text{JA}} \text{vs. Air Flow Table for 32 Lead LQFP}$ 

### $\theta_{1A}$ by Velocity (Linear Feet per Minute)

	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	67.8°C/W	55.9°C/W	50.1°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	47.9°C/W	42.1°C/W	39.4°C/W

**NOTE:** Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for ICS85310I-31 is: 1216



## Low Skew, Dual, 1-to-5 2.5V/3.3V Differential-to-ECL/LVPECL Fanout Buffer

### PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

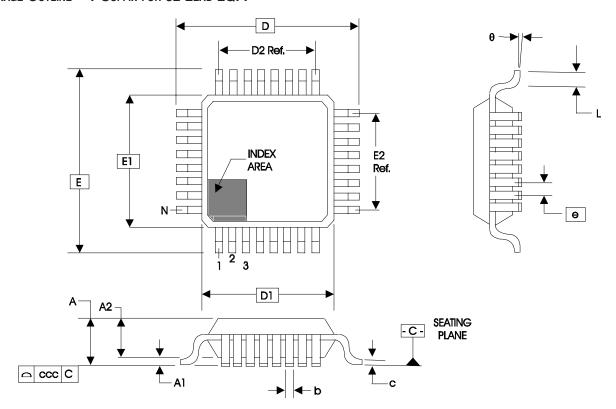


TABLE 8. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS						
0,4150		BBA				
SYMBOL	МІМІМИМ	NOMINAL	MAXIMUM			
N		32				
Α			1.60			
A1	0.05		0.15			
A2	1.35	1.40	1.45			
b	0.30	0.37	0.45			
С	0.09		0.20			
D		9.00 BASIC				
D1		7.00 BASIC				
D2		5.60 Ref.				
E		9.00 BASIC				
E1		7.00 BASIC				
E2		5.60 Ref.				
е		0.80 BASIC				
L	0.45	0.60	0.75			
θ	0°		7°			
ccc			0.10			

Reference Document: JEDEC Publication 95, MS-026



Low Skew, Dual, 1-to-5 2.5V/3.3V Differential-to-ECL/LVPECL Fanout Buffer

#### Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
85310AYI-31	ICS85310AYI31	32 lead LQFP	tray	-40°C to 85°C
85310AYI-31T	ICS85310AYI31	32 lead LQFP	1000 tape & reel	-40°C to 85°C
85310AYI-31LF	ICS5310Al31L	32 lead "Lead Free" LQFP	tray	-40°C to 85°C
85310AYI-31LFT	ICS5310Al31L	32 lead "Lead Free" LQFP	1000 tape & reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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# Low Skew, Dual, 1-to-5 and 2.5 V/3.3 V DIFFERENTIAL-TO-ECL/LVPECL FANOUT BUFFER

REVISION HISTORY SHEET					
Rev	Table	Page	Description of Change		
Α		9	Added Termination for LVPECL Outputs.		
А			Updated part number from ICS85310-31 to ICS85310I-31 throughout the data sheet to reflect operating temperature.		
Α	T9	14	Corrected Marking from ICS85310AYI-31 to ICS85310AYI31.		
B T4A	T4A	4	Power Supply table - increased max. value for I <sub>EE</sub> to 120mA from 30mA max.	10/23/02	
		10	Power Considerations have re-adjusted to the increased I <sub>EE</sub> value.		
	T2	2	Pin Characteristics Table - changed 4pF max. to 4pF typical.		
T4D	4	Updated Absolute Maximum Ratings.			
	5	LVPECL DC Characteristics Table - changed V <sub>SWING</sub> from 0.85V max. to 1.0V max.			
С		8 & 9	Application section added, <i>Termination for 2.5V LVPECL Outputs</i> and <i>Differential Clock Input Interface</i> .	7/31/03	
		10 & 11	Power Considerations - recalculated Total Power Dissipation for 3.8V.		
		14	Ordering Information Table - corrected marking from ICS85310AYI31 to ICS85310AI-31.		
D T5		1	Features Section - added Additive Phase Jitter bullet and Lead-Free bullet.	7/6/05	
	T5	5	AC Characteristics Table - added Additive Phase Jitter row.		
	T9	6 14	Added Additive Phase Jitter Section.  Ordering Information Table - added Lead-Free Part Number and Note.		
	T4D	5	LVPECL DC Characteristics Table -corrected V <sub>OH</sub> max. from V <sub>CCO</sub> - 1.0V to V <sub>CCO</sub> -		
E			0.9V.	4/11/07	
		10 - 11	Power Considerations - corrected power dissipation to reflect V <sub>OH</sub> max in Table		
			4D.		
Е Т9			Updated datasheet's header/footer with IDT from ICS.	12/8/10	
	Т9	15	Removed ICS prefix from Part/Order Number column.		
		17	Added Contact Page.		



Low Skew, Dual, 1-to-5 2.5V/3.3V Differential-to-ECL/LVPECL Fanout Buffer

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